

Supplementary material

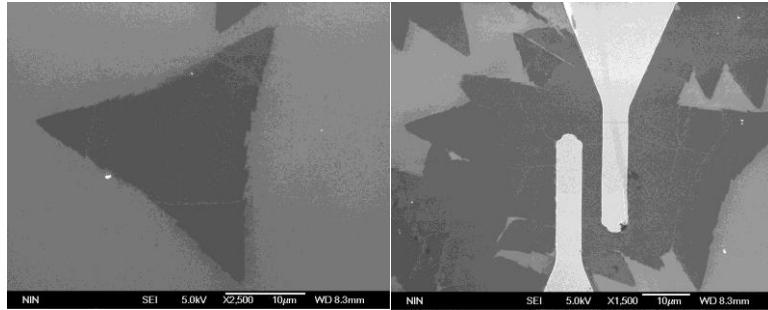


Figure S1. The SEM images of monolayer MoS₂ and transistor.

Table S1. Comparison of the performance of device with literature.

Ref.	Materials	Ion/Ioff Ratio	On-state Current(A)	Dielectric	Structure	Process complexity
Our result	MoS ₂	$\sim 1 \times 10^4$	2×10^{-7}	300nm SiO ₂	Horizontal-gate	I
[1]	MoS ₂	$\sim 1 \times 10^4$	3×10^{-6}	90nm SiO ₂	Back-gate	II
[2]	MoS ₂	$\sim 1 \times 10^4$	3×10^{-7}	SiO ₂	Back-gate	II
[3]	MoS ₂	$\sim 10^6$	1×10^{-6}	Al ₂ O ₃ /HfO ₂	Dual-gate	IV
[4]	MoS ₂ /BP	$\sim 10^4$	1×10^{-7}	Ion gel(top)	Top-gate	III
[5]	WSe ₂ /SnSe ₂	$\sim 10^5$	9×10^{-7}	40nm Al ₂ O ₃ (bottom)	Back-gate	II

Process complexity progressively increases from I to IV.

Table S2. Typical values of parameters in equations.

parameters		Value
L(μm)	Length of channel	8
W(μm)	Width of channel	40
t _{ox} (nm)	Thickness of oxide	300
g _m (S)	Trans-conductance	di_{ds}/dv_{gs}
C _{ox} (F/μm ²)	Gate capacitance per unit area	1.15×10^{-4}
μ ₀ (cm ² /V • s)	Mobility	2.06
V _{th} (V)	Threshold voltage	-16
R _{total} (Ω)	Total resistance	v_{ds}/i_{ds}
A [*] (A/(cm ² • K ²))	Richardson's coefficient	120
k(J/K)	Boltzmann constant	1.380649×10^{-23}
T(K)	Temperature	300

References

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